Session Title:	[ME2] Packaging Material/Analysis
Session Date:	November 14 (Mon.), 2022
Session Time:	15:00-17:00
Session Room:	Room E (Grand Ballroom 3, 2F)
Session Chair:	Prof. Hyuk Jun Kwon (DGIST, Korea)

[ME2-1] [Invited] 15:00-15:30

Heterogeneous Integration in Memory Application and the Contribution of Electronic Packaging Technology

Jong Hoon Kim, Ki-Ill Moon, and Kangwook Lee (SK hynix, Korea)

[ME2-2] [Invited] 15:30-16:00

Tiling Bonding Process, Enabling Technology for Chiplet Integration

Kwang-Seong Choi, Jiho Joo, Yong-Sung Eom, Gwang-Mun Choi, Ho-Gyeong Yun, Seok Hwan Moon, Chanmi Lee, Ki-Seok Jang, Jin-Hyuk Oh, In-seok Kye, and Yoon-Hwan Moon (ETRI, Korea)

[ME2-3] 16:00-16:20

Adhesive-Free Bonding of Polymer Substrates for Flexible Devices

Tae-Ik Lee (KITECH, Korea)

[ME2-4] 16:20-16:40

Prediction of Solder Fatigue Life of Package by Automated Parametric Modeling Simulation Technique

Hak-Sung Kim (Hanyang Univ., Korea)

[ME2-5] 16:40-17:00

Effects of Dielectric Process Condition on the Interfacial Characteristics of Polyimide Capping Layer/Cu RDL Structure for Fan-out Package

Doheon Kim, Gahui Kim, and Young-Bae Park (Andong Nat'l Univ., Korea)